

| ENGINEERING DEPT. | | PRODUCT SPECIFICATION | SPEC.NO.: | SPCI057C |
|-------------------|----------|---|-----------|----------|
| REVISIONS | ECN11185 | For CI01 Latch Type Series Connector System | PAGE: | 1/5 |

1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and procedure with terminals crimped on the specified maximum size wire

2. APPLICABLE STANDARDS:

MIL - STD - 202 MIL - STD - 1344 Methods for test of connectors for electronic equipment

Test methods for electrical connectors

3. APPLICABLE SERIES NO: CI01 With Latch Type Series

4. SHAPE, CONSTRUCTION AND DIMENSIONS See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

6.1 Thickness: $0.8 \text{ mm} (.031'') \sim 1.6 \text{ mm} (.063'')$ 6.2 P.C. Board Layout: See attached drawings



REVIEWED: David APPROVED: Eisley VERIFIED: Karen .



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7. ELECTRICAL PERFORMANCE:

| | ITEM | TEST CONDITION | REQUIREMENT |
|-----|---------------------------|---|----------------------------------|
| 7.1 | Rated current and voltage | | 2A 250V AC/DC (r.m.s.) |
| 7.2 | Contact resistance | Dry circuit of DC 20 mV max., 100 mA max. | Less than $20 \text{ m}\Omega$ |
| 7.3 | Dielectric strength | When applied AC 800 V 1 minute between adjacent terminal | No change |
| 7.4 | Insulation resistance | When applied DC 500 V between adjacent terminal or ground | More than $1000 \text{M}\Omega$ |

8. MECHANICAL PERFORMANCE:

| | ITEM | TEST CONDITION | REQUIREMENT |
|-----|--------------------------------------|---|---|
| 8.1 | Wire size | Specified wire size | Accepts AWG#24~#30 |
| 8.2 | Terminal crimp Tensile | When crimped AWG#24 size wire | 3.0 Kgf (29.4 N) Min. |
| | strength | When crimped AWG#26 size wire | 2.0 Kgf (19.6 N) Min. |
| | | When crimped AWG#28 size wire | 1.3 Kgf (12.7 N) Min. |
| | | When crimped AWG#30 size wire | 0.8 Kgf (7.8 N) Min. |
| 8.3 | Terminal insertion force | Insertion speed 25± 3 mm per minute into housing | 0.6 Kgf (5.9 N) Max. |
| 8.4 | Contact retaining force in insulator | Retention speed 25± 3 mm per minute from housing | 1.5 Kgf (14.7 N) Min. |
| 8.5 | Single contact insertion force | Measure force to insertion using 0.50 mm square pin at speed 25± 3 mm per minute | 0.7 Kgf (6.9 N) Max. |
| 8.6 | Single contact withdrawal force | Measure force to withdrawal using 0.50 mm square pin at speed 25± 3 mm per minute | 0.10 Kgf (0.98 N) Min. |
| 8.7 | Durability | Connector shall be subjected to 30 cycles of insertion and withdrawal | Contact resistance: Less than twice of initial |
| 8.8 | Pin retention force | Push pin from insulator base at speed | More than 1.0 Kgf |
| | | 25± 3 mm per minute | |



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| | ITEM | TEST CONDITION | | REQUIREMENT | |
|------|---|--|-------|---------------|--------------------|
| 8.9 | Mating and Unmating force(Remove Latch) | Speed 25± 3 mm per minute | | Mating (Max.) | Unmating (Min.) |
| | | | 10PIN | 6.0 kgf | 1.4 kgf |
| | | | 12PIN | 6.0 kgf | 1.4 kgf |
| | | | 14PIN | 8.0 kgf | 2.0 kgf |
| | | | 16PIN | 10.0 kgf | 2.5 kgf |
| 8.10 | Lock Force | The unmating force is measured with only base without terminal | | More than 6. | .0 Kgf |

9. ENVIRONMENTAL PERFORMANCE:

| | ITEM | TEST CONDITION | REQUIREMENT |
|-----|-------------------------|---|---|
| 9.1 | Temperature rise | Then carried the rated current | 30°C max. |
| 9.2 | Vibration | 1.5 mm 10-55-10 HZ / minute each 2 hours for X , Y and Z directions | Appearance: No damage Discontinuity: 1 micro second max. |
| 9.3 | Solderability | Tin-Lead Process: | Minimum: |
| | | Soldering time: 5 ± 0.5 second | 90% of immersed area |
| | | Soldering pot: 230 ± 5°C | |
| | | Lead-Free Process: | |
| | | Soldering time: 3 ± 0.5 second | |
| | | Soldering pot: 245 ± 5°C | |
| 9.4 | Resistance to soldering | Tin-Lead Process for DIP Type: | No damage |
| | heat | Soldering time: 5 ± 0.5 second | |
| | | Soldering pot: 260 ± 5 °C | |
| | | Tin-Lead Process for SMT Type: | |
| | | Refer Reflow temperature profile(12.1) | |
| | | Lead-Free Process for SMT Type: | |
| | | Refer Reflow temperature profile(12.2) | |
| 9.5 | Heat aging | 105 ± 2°C , 96 hours | No damage |



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| | ITEM | TEST CONDITION | REQUIREMENT |
|-----|---------------------|---|--|
| 9.6 | Humidity | 40 ± 2 °C , 90-95% RH , 96 hours measurement must be taken within 30 min. after tested | Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3 |
| 9.7 | Temperature cycling | One cycle consists of: (1)-55 +0 °C, 30 min. (2)Room temp. 10-15 min. (3) 85+3 °C, 30 min. (4)Room temp. 10-15 min. | Appearance: No damage Contact resistance: Less than twice of initial |
| 9.8 | Salt spray | Temperature: 35 ± 3°C Solution: 5 ± 1% Spray time: 48 ± 4 hours Measurement must be taken after water rinse | Appearance: No damage Contact resistance: Less than twice of initial |

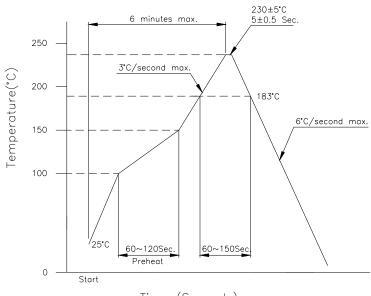
10. AMBIENT TEMPERATURE RANGE: -25 to + 105°C



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11. Recommended IR Reflow Temperature Profile:

11.1 Using Typical Solder Paste



Time (Seconds)

12.2 Using Lead-Free Solder Paste

